

TRANSMITTAL

Electronic Version v1.1

Stylesheet Version v1.1.0

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|--|--|----------------|---------------|-------------|----------------|--|---------------|----------|
| Title of Invention | [MOLD AND METHOD OF MOLDING SEMICONDUCTOR DEVICES] | | | | | | | |
| Application Number : | | | | | | | | |
| Date : | | | | | | | | |
| First Named Applicant: | Mr. Jen-Chieh Kao | | | | | | | |
| Confirmation Number: | | | | | | | | |
| Attorney Docket Number: | 11184-US-PA | | | | | | | |
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| <table border="1"><tr><td>Submitted By:</td><td>Elec. Sign.</td><td>Sign. Capacity</td></tr><tr><td>Dr. Belinda Lee Registered Number: 46,863</td><td>/Belinda Lee/</td><td>Inventor</td></tr></table> | | | Submitted By: | Elec. Sign. | Sign. Capacity | Dr. Belinda Lee Registered Number: 46,863 | /Belinda Lee/ | Inventor |
| Submitted By: | Elec. Sign. | Sign. Capacity | | | | | | |
| Dr. Belinda Lee Registered Number: 46,863 | /Belinda Lee/ | Inventor | | | | | | |

| Documents being submitted: | Files |
|----------------------------|--|
| us-fee-sheet | 11184-usfees.xml us-fee-sheet.xsl us-fee-sheet.dtd |
| us-assignment | 11184-usassn.xml us-assignment.xsl us-assignment.dtd 11184assignment1.tif 11184assignment2.tif |
| us-request | 11184-usrequ.xml us-request.dtd us-request.xsl |
| us-declaration | 11184declaration1.tif |
| us-declaration | 11184declaration2.tif |
| application-body | 11184-trans.xml us-application-body.xsl application-body.dtd wipo.ent mathml2.dtd mathml2-qname-1.mod isoamsa.ent isoamsb.ent isoamsc.ent isoamsn.ent isoamso.ent isoamsr.ent isogr3.ent isomfrk.ent isomopf.ent isomscr.ent isotech.ent isobox.ent isocyr1.ent isocyr2.ent isodia.ent isolat1.ent isolat2.ent isonum.ent isopub.ent mmlextra.ent mmlalias.ent soextblx.dtd 11184us0001.tif 11184us0002.tif 11184us0003.tif 11184us0004.tif 11184us0005.tif 11184us0006.tif 11184us0007.tif 11184us0008.tif |

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Comments

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